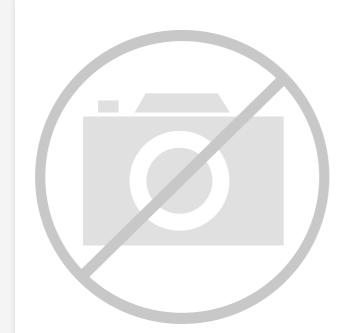
# E·XFL

# Intel - 10AT115S2F45E2SGE2 Datasheet



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#### Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

#### **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

## Details

Details	
Product Status	Active
Number of LABs/CLBs	427200
Number of Logic Elements/Cells	1150000
Total RAM Bits	68857856
Number of I/O	624
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 100°C (TJ)
Package / Case	1932-BBGA, FCBGA
Supplier Device Package	1932-FCBGA (45x45)
Purchase URL	https://www.e-xfl.com/product-detail/intel/10at115s2f45e2sge2

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



# Intel<sup>®</sup> Arria<sup>®</sup> 10 Device Overview

The Intel<sup>®</sup> Arria<sup>®</sup> 10 device family consists of high-performance and power-efficient 20 nm mid-range FPGAs and SoCs.

Intel Arria 10 device family delivers:

- Higher performance than the previous generation of mid-range and high-end FPGAs.
- Power efficiency attained through a comprehensive set of power-saving technologies.

The Intel Arria 10 devices are ideal for high performance, power-sensitive, midrange applications in diverse markets.

Market	Applications
Wireless	<ul><li>Channel and switch cards in remote radio heads</li><li>Mobile backhaul</li></ul>
Wireline	<ul> <li>40G/100G muxponders and transponders</li> <li>100G line cards</li> <li>Bridging</li> <li>Aggregation</li> </ul>
Broadcast	<ul> <li>Studio switches</li> <li>Servers and transport</li> <li>Videoconferencing</li> <li>Professional audio and video</li> </ul>
Computing and Storage	<ul><li>Flash cache</li><li>Cloud computing servers</li><li>Server acceleration</li></ul>
Medical	<ul><li>Diagnostic scanners</li><li>Diagnostic imaging</li></ul>
Military	<ul> <li>Missile guidance and control</li> <li>Radar</li> <li>Electronic warfare</li> <li>Secure communications</li> </ul>

#### Table 1. Sample Markets and Ideal Applications for Intel Arria 10 Devices

#### **Related Information**

Intel Arria 10 Device Handbook: Known Issues Lists the planned updates to the *Intel Arria 10 Device Handbook* chapters.

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Feature	Description				
Low-power serial transceivers	<ul> <li>Continuous operating range: <ul> <li>Intel Arria 10 GX-1 Gbps to 17.4 Gbps</li> <li>Intel Arria 10 GT-1 Gbps to 25.8 Gbps</li> </ul> </li> <li>Backplane support: <ul> <li>Intel Arria 10 GX—up to 12.5</li> <li>Intel Arria 10 GT—up to 12.5</li> </ul> </li> <li>Extended range down to 125 Mbps with oversampling</li> <li>ATX transmit PLLs with user-configurable fractional synthesis capability</li> <li>Electronic Dispersion Compensation (EDC) support for XFP, SFP+, QSFP, and CFP optical module</li> <li>Adaptive linear and decision feedback equalization</li> <li>Transmitter pre-emphasis and de-emphasis</li> <li>Dynamic partial reconfiguration of individual transceiver channels</li> </ul>				
HPS (Intel Arria 10 SX devices only)	Processor and system       • Dual-core ARM Cortex-A9 MPCore processor—1.2 GHz CPU with 1.5 GHz overdrive capability         • 256 KB on-chip RAM and 64 KB on-chip ROM         • System peripherals—general-purpose timers, watchdog timers, di memory access (DMA) controller, FPGA configuration manager, ar clock and reset managers         • Security features—anti-tamper, secure boot, Advanced Encryptior Standard (AES) and authentication (SHA)         • ARM CoreSight* JTAG debug access port, trace port, and on-chip trace storage	nd n			
	<ul> <li>External interfaces</li> <li>Hard memory interface—Hard memory controller (2,400 Mbps DE and 2,133 Mbps DDR3), Quad serial peripheral interface (QSPI) fl controller, NAND flash controller, direct memory access (DMA) controller, Secure Digital/MultiMediaCard (SD/MMC) controller</li> <li>Communication interface—10/100/1000 Ethernet media access control (MAC), USB On-The-GO (OTG) controllers, I<sup>2</sup>C controllers, UART 16550, serial peripheral interface (SPI), and up to 62 HPS GPIO interfaces (48 direct-share I/Os)</li> </ul>	lash			
	Interconnects to core       • High-performance ARM AMBA* AXI bus bridges that support simultaneous read and write         • HPS-FPGA bridges—include the FPGA-to-HPS, HPS-to-FPGA, and lightweight HPS-to-FPGA bridges that allow the FPGA fabric to iss transactions to slaves in the HPS, and vice versa         • Configuration bridge that allows HPS configuration manager to configure the core logic via dedicated 32-bit configuration port         • FPGA-to-HPS SDRAM controller bridge—provides configuration interfaces for the multiport front end (MPFE) of the HPS SDRAM controller				
Configuration	<ul> <li>Tamper protection—comprehensive design protection to protect your valuable IP investment</li> <li>Enhanced 256-bit advanced encryption standard (AES) design security with authentication</li> <li>Configuration via protocol (CvP) using PCIe Gen1, Gen2, or Gen3</li> </ul>				
	continue	d			

 $<sup>^{(2)}\,</sup>$  Intel Arria 10 devices support this external memory interface using hard PHY with soft memory controller.



Feature	Description					
	<ul> <li>Dynamic reconfiguration of the transceivers and PLLs</li> <li>Fine-grained partial reconfiguration of the core fabric</li> <li>Active Serial x4 Interface</li> </ul>					
Power management	<ul> <li>SmartVID</li> <li>Low static power device options</li> <li>Programmable Power Technology</li> <li>Intel Quartus Prime integrated power analysis</li> </ul>					
Software and tools	<ul> <li>Intel Quartus Prime design suite</li> <li>Transceiver toolkit</li> <li>Platform Designer system integration tool</li> <li>DSP Builder for Intel FPGAs</li> <li>OpenCL<sup>™</sup> support</li> <li>Intel SoC FPGA Embedded Design Suite (EDS)</li> </ul>					

## **Related Information**

#### Intel Arria 10 Transceiver PHY Overview Provides details on Intel Arria 10 transceivers.

# **Intel Arria 10 Device Variants and Packages**

## Table 4. Device Variants for the Intel Arria 10 Device Family

Variant	Description
Intel Arria 10 GX	FPGA featuring 17.4 Gbps transceivers for short reach applications with 12.5 backplane driving capability.
Intel Arria 10 GT	<ul> <li>FPGA featuring:</li> <li>17.4 Gbps transceivers for short reach applications with 12.5 backplane driving capability.</li> <li>25.8 Gbps transceivers for supporting CAUI-4 and CEI-25G applications with CFP2 and CFP4 modules.</li> </ul>
Intel Arria 10 SX	SoC integrating ARM-based HPS and FPGA featuring 17.4 Gbps transceivers for short reach applications with 12.5 backplane driving capability.

# **Intel Arria 10 GX**

This section provides the available options, maximum resource counts, and package plan for the Intel Arria 10 GX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Intel FPGA Product Selector.

## **Related Information**

## Intel FPGA Product Selector

Provides the latest information on Intel products.



ES : Engineering sample

RoHS

**FPGA Fabric** 

Speed Grade

1 (fastest)

2 3

G : RoHS6 N : RoHS5 Contact Intel P : Leaded for availability

## **Available Options**

Family Variant .....

090 : 900K logic elements 115 : 1,150K logic elements

25.8 Gbps transceivers

Transceiver

1 (fastest)

2

Speed Grade

T : GT variant

Logic Density



Package Code

45 : 1,932 pins, 45 mm x 45 mm

## Figure 2. Sample Ordering Code and Available Options for Intel Arria 10 GT Devices



## **Maximum Resources**

#### Table 10. Maximum Resource Counts for Intel Arria 10 GT Devices

Reso	urce	Produ	ct Line
		GT 900	GT 1150
Logic Elements (LE) (K)		900	1,150
ALM		339,620	427,200
Register		1,358,480	1,708,800
Memory (Kb)	M20K	48,460	54,260
	MLAB	9,386	12,984
Variable-precision DSP Block		1,518	1,518
18 x 19 Multiplier		3,036	3,036
PLL	Fractional Synthesis	32	32
	I/O	16	16
Transceiver	17.4 Gbps	72 (5)	72 <sup>(5)</sup>
	25.8 Gbps	6	6
GPIO <sup>(6)</sup>		624	624
LVDS Pair <sup>(7)</sup>		312	312
PCIe Hard IP Block		4	4
Hard Memory Controller		16	16

## **Related Information**

#### Intel Arria 10 GT Channel Usage

Configuring GT/GX channels in Intel Arria 10 GT devices.

## Package Plan

## Table 11.Package Plan for Intel Arria 10 GT Devices

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	SF45 (45 mm × 45 mm, 1932-pin FBGA)				
	3 V I/O	LVDS I/O	XCVR		
GT 900	—	624	72		
GT 1150	_	624	72		

<sup>&</sup>lt;sup>(5)</sup> If all 6 GT channels are in use, 12 of the GX channels are not usable.

<sup>&</sup>lt;sup>(6)</sup> The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

<sup>&</sup>lt;sup>(7)</sup> Each LVDS I/O pair can be used as differential input or output.



## **Related Information**

I/O and High-Speed Differential I/O Interfaces in Intel Arria 10 Devices chapter, Intel Arria 10 Device Handbook

Provides the number of 3 V and LVDS I/Os, and LVDS channels for each Intel Arria 10 device package.

## **Intel Arria 10 SX**

This section provides the available options, maximum resource counts, and package plan for the Intel Arria 10 SX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Intel FPGA Product Selector.

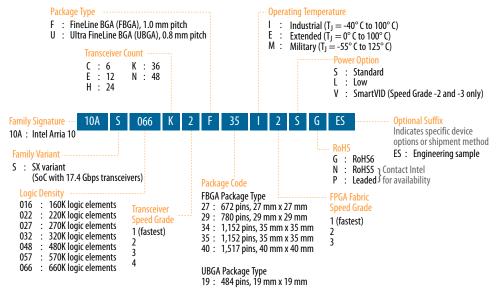
## **Related Information**

Intel FPGA Product Selector

Provides the latest information on Intel products.

## **Available Options**

#### Figure 3. Sample Ordering Code and Available Options for Intel Arria 10 SX Devices



#### **Related Information**

Transceiver Performance for Intel Arria 10 GX/SX Devices Provides more information about the transceiver speed grade.



## **Maximum Resources**

## Table 12. Maximum Resource Counts for Intel Arria 10 SX Devices

Reso	ource			I	Product Line			
		SX 160	SX 220	SX 270	SX 320	SX 480	SX 570	SX 660
Logic Elements	s (LE) (K)	160	220	270	320	480	570	660
ALM		61,510	80,330	101,620	119,900	183,590	217,080	251,680
Register		246,040	321,320	406,480	479,600	734,360	868,320	1,006,720
Memory (Kb)	M20K	8,800	11,740	15,000	17,820	28,620	36,000	42,620
	MLAB	1,050	1,690	2,452	2,727	4,164	5,096	5,788
Variable-precision DSP Block		156	192	830	985	1,368	1,523	1,687
18 x 19 Multip	lier	312	384	1,660	1,970	2,736	3,046	3,374
PLL	Fractional Synthesis	6	6	8	8	12	16	16
	I/O	6	6	8	8	12	16	16
17.4 Gbps Tra	nsceiver	12	12	24	24	36	48	48
GPIO <sup>(8)</sup>		288	288	384	384	492	696	696
LVDS Pair <sup>(9)</sup>		120	120	168	168	174	324	324
PCIe Hard IP E	Block	1	1	2	2	2	2	2
Hard Memory	Controller	6	6	8	8	12	16	16
ARM Cortex-As Processor	9 MPCore	Yes	Yes	Yes	Yes	Yes	Yes	Yes

## Package Plan

# Table 13.Package Plan for Intel Arria 10 SX Devices (U19, F27, F29, and F34)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

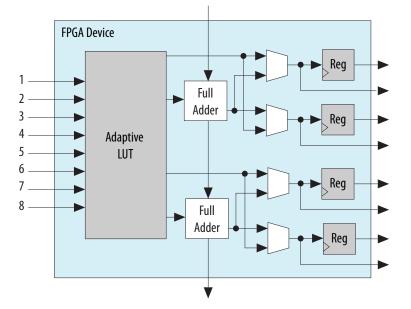
Product Line	duct Line U19 (19 mm × 19 mm, 484-pin UBGA)		F27 (27 mm × 27 mm, 672-pin FBGA)		F29 (29 mm × 29 mm, 780-pin FBGA)		F34 (35 mm × 35 mm, 1152-pin FBGA)					
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
SX 160	48	144	6	48	192	12	48	240	12	_	-	-
SX 220	48	144	6	48	192	12	48	240	12	_	-	-
SX 270	-	-	_	48	192	12	48	312	12	48	336	24
SX 320	-	-	_	48	192	12	48	312	12	48	336	24
	continued											

<sup>&</sup>lt;sup>(8)</sup> The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

<sup>(9)</sup> Each LVDS I/O pair can be used as differential input or output.



## Figure 5. ALM for Intel Arria 10 Devices



The Intel Quartus Prime software optimizes your design according to the ALM logic structure and automatically maps legacy designs into the Intel Arria 10 ALM architecture.

# **Variable-Precision DSP Block**

The Intel Arria 10 variable precision DSP blocks support fixed-point arithmetic and floating-point arithmetic.

Features for fixed-point arithmetic:

- High-performance, power-optimized, and fully registered multiplication operations
- 18-bit and 27-bit word lengths
- Two 18 x 19 multipliers or one 27 x 27 multiplier per DSP block
- Built-in addition, subtraction, and 64-bit double accumulation register to combine multiplication results
- Cascading 19-bit or 27-bit when pre-adder is disabled and cascading 18-bit when pre-adder is used to form the tap-delay line for filtering applications
- Cascading 64-bit output bus to propagate output results from one block to the next block without external logic support
- Hard pre-adder supported in 19-bit and 27-bit modes for symmetric filters
- Internal coefficient register bank in both 18-bit and 27-bit modes for filter implementation
- 18-bit and 27-bit systolic finite impulse response (FIR) filters with distributed output adder
- Biased rounding support



Variant	Product Line	precision		put and Output ns Operator	18 x 19 Multiplier	18 x 18 Multiplier
		DSP Block	18 x 19 Multiplier	27 x 27 Multiplier	Adder Sum Mode	Adder Summed with 36 bit Input
	SX 320	984	1,968	984	984	984
	SX 480	1,368	2,736	1,368	1,368	1,368
	SX 570	1,523	3,046	1,523	1,523	1,523
	SX 660	1,687	3,374	1,687	1,687	1,687

## Table 17. Resources for Floating-Point Arithmetic in Intel Arria 10 Devices

The table lists the variable-precision DSP resources by bit precision for each Intel Arria 10 device.

Variant	Product Line	Variable- precision DSP Block	Single Precision Floating-Point Multiplication Mode	Single-Precision Floating-Point Adder Mode	Single- Precision Floating-Point Multiply Accumulate Mode	Peak Giga Floating- Point Operations per Second (GFLOPs)
Intel Arria 10 GX	GX 160	156	156	156	156	140
GA	GX 220	192	192	192	192	173
	GX 270	830	830	830	830	747
	GX 320	984	984	984	984	886
	GX 480	1,369	1,368	1,368	1,368	1,231
	GX 570	1,523	1,523	1,523	1,523	1,371
	GX 660	1,687	1,687	1,687	1,687	1,518
	GX 900	1,518	1,518	1,518	1,518	1,366
	GX 1150	1,518	1,518	1,518	1,518	1,366
Intel Arria 10	GT 900	1,518	1,518	1,518	1,518	1,366
GT	GT 1150	1,518	1,518	1,518	1,518	1,366
Intel Arria 10	SX 160	156	156	156	156	140
SX	SX 220	192	192	192	192	173
	SX 270	830	830	830	830	747
	SX 320	984	984	984	984	886
	SX 480	1,369	1,368	1,368	1,368	1,231
	SX 570	1,523	1,523	1,523	1,523	1,371
	SX 660	1,687	1,687	1,687	1,687	1,518

# **Embedded Memory Blocks**

The embedded memory blocks in the devices are flexible and designed to provide an optimal amount of small- and large-sized memory arrays to fit your design requirements.



# **Types of Embedded Memory**

The Intel Arria 10 devices contain two types of memory blocks:

- 20 Kb M20K blocks—blocks of dedicated memory resources. The M20K blocks are ideal for larger memory arrays while still providing a large number of independent ports.
- 640 bit memory logic array blocks (MLABs)—enhanced memory blocks that are configured from dual-purpose logic array blocks (LABs). The MLABs are ideal for wide and shallow memory arrays. The MLABs are optimized for implementation of shift registers for digital signal processing (DSP) applications, wide and shallow FIFO buffers, and filter delay lines. Each MLAB is made up of ten adaptive logic modules (ALMs). In the Intel Arria 10 devices, you can configure these ALMs as ten 32 x 2 blocks, giving you one 32 x 20 simple dual-port SRAM block per MLAB.

# **Embedded Memory Capacity in Intel Arria 10 Devices**

	Product	M2	:0K	ML	MLAB		
Variant	Line	Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	Total RAM Bit (Kb)	
Intel Arria 10 GX	GX 160	440	8,800	1,680	1,050	9,850	
	GX 220	587	11,740	2,703	1,690	13,430	
	GX 270	750	15,000	3,922	2,452	17,452	
	GX 320	891	17,820	4,363	2,727	20,547	
	GX 480	1,431	28,620	6,662	4,164	32,784	
	GX 570	1,800	36,000	8,153	5,096	41,096	
	GX 660	2,131	42,620	9,260	5,788	48,408	
	GX 900	2,423	48,460	15,017	9,386	57,846	
	GX 1150	2,713	54,260	20,774	12,984	67,244	
Intel Arria 10 GT	GT 900	2,423	48,460	15,017	9,386	57,846	
	GT 1150	2,713	54,260	20,774	12,984	67,244	
Intel Arria 10 SX	SX 160	440	8,800	1,680	1,050	9,850	
	SX 220	587	11,740	2,703	1,690	13,430	
	SX 270	750	15,000	3,922	2,452	17,452	
	SX 320	891	17,820	4,363	2,727	20,547	
	SX 480	1,431	28,620	6,662	4,164	32,784	
	SX 570	1,800	36,000	8,153	5,096	41,096	
	SX 660	2,131	42,620	9,260	5,788	48,408	

#### Table 18. Embedded Memory Capacity and Distribution in Intel Arria 10 Devices



The fractional synthesis PLLs support the following features:

- Reference clock frequency synthesis for transceiver CMU and Advanced Transmit (ATX) PLLs
- Clock network delay compensation
- Zero-delay buffering
- Direct transmit clocking for transceivers
- Independently configurable into two modes:
  - Conventional integer mode equivalent to the general purpose PLL
  - Enhanced fractional mode with third order delta-sigma modulation
- PLL cascading

## I/O PLLs

The integer mode I/O PLLs are located in each bank of 48 I/Os. You can use the I/O PLLs to simplify the design of external memory and high-speed LVDS interfaces.

In each I/O bank, the I/O PLLs are adjacent to the hard memory controllers and LVDS SERDES. Because these PLLs are tightly coupled with the I/Os that need to use them, it makes it easier to close timing.

You can use the I/O PLLs for general purpose applications in the core such as clock network delay compensation and zero-delay buffering.

Intel Arria 10 devices support PLL-to-PLL cascading.

# **FPGA General Purpose I/O**

Intel Arria 10 devices offer highly configurable GPIOs. Each I/O bank contains 48 general purpose I/Os and a high-efficiency hard memory controller.

The following list describes the features of the GPIOs:

- Consist of 3 V I/Os for high-voltage application and LVDS I/Os for differential signaling
  - $-\,$  Up to two 3 V I/O banks, available in some devices, that support up to 3 V I/O standards
  - LVDS I/O banks that support up to 1.8 V I/O standards
- Support a wide range of single-ended and differential I/O interfaces
- LVDS speeds up to 1.6 Gbps
- Each LVDS pair of pins has differential input and output buffers, allowing you to configure the LVDS direction for each pair.
- Programmable bus hold and weak pull-up
- Programmable differential output voltage (V<sub>OD</sub>) and programmable pre-emphasis



### Table 20. Memory Standards Supported by the Hard Memory Controller

This table lists the overall capability of the hard memory controller. For specific details, refer to the External Memory Interface Spec Estimator and Intel Arria 10 Device Datasheet.

Memory Standard	Rate Support	Ping Pong PHY Support	Maximum Frequency (MHz)
DDR4 SDRAM	Quarter rate	Yes	1,067
		_	1,200
DDR3 SDRAM	Half rate	Yes	533
		_	667
	Quarter rate	Yes	1,067
		_	1,067
DDR3L SDRAM	Half rate	Yes	533
		_	667
	Quarter rate	Yes	933
		_	933
LPDDR3 SDRAM	Half rate	-	533
	Quarter rate	_	800

## Table 21. Memory Standards Supported by the Soft Memory Controller

Memory Standard	Rate Support	Maximum Frequency (MHz)
RLDRAM 3 (11)	Quarter rate	1,200
QDR IV SRAM <sup>(11)</sup>	Quarter rate	1,067
QDR II SRAM	Full rate	333
	Half rate	633
QDR II+ SRAM	Full rate	333
	Half rate	633
QDR II+ Xtreme SRAM	Full rate	333
	Half rate	633

## Table 22. Memory Standards Supported by the HPS Hard Memory Controller

The hard processor system (HPS) is available in Intel Arria 10 SoC devices only.

Memory Standard	Rate Support	Maximum Frequency (MHz)
DDR4 SDRAM	Half rate	1,200
DDR3 SDRAM	Half rate	1,067
DDR3L SDRAM	Half rate	933

<sup>&</sup>lt;sup>(11)</sup> Intel Arria 10 devices support this external memory interface using hard PHY with soft memory controller.



Each transceiver channel contains a channel PLL that can be used as the CMU PLL or clock data recovery (CDR) PLL. In CDR mode, the channel PLL recovers the receiver clock and data in the transceiver channel. Up to 80 independent data rates can be configured on a single Intel Arria 10 device.

## Table 23. PMA Features of the Transceivers in Intel Arria 10 Devices

Feature	Capability
Chip-to-Chip Data Rates	1 Gbps to 17.4 Gbps (Intel Arria 10 GX devices) 1 Gbps to 25.8 Gbps (Intel Arria 10 GT devices)
Backplane Support	Drive backplanes at data rates up to 12.5 Gbps
Optical Module Support	SFP+/SFP, XFP, CXP, QSFP/QSFP28, CFP/CFP2/CFP4
Cable Driving Support	SFP+ Direct Attach, PCI Express over cable, eSATA
Transmit Pre-Emphasis	4-tap transmit pre-emphasis and de-emphasis to compensate for system channel loss
Continuous Time Linear Equalizer (CTLE)	Dual mode, high-gain, and high-data rate, linear receive equalization to compensate for system channel loss
Decision Feedback Equalizer (DFE)	7-fixed and 4-floating tap DFE to equalize backplane channel loss in the presence of crosstalk and noisy environments
Variable Gain Amplifier	Optimizes the signal amplitude prior to the CDR sampling and operates in fixed and adaptive modes
Altera Digital Adaptive Parametric Tuning (ADAPT)	Fully digital adaptation engine to automatically adjust all link equalization parameters— including CTLE, DFE, and variable gain amplifier blocks—that provide optimal link margin without intervention from user logic
Precision Signal Integrity Calibration Engine (PreSICE)	Hardened calibration controller to quickly calibrate all transceiver control parameters on power-up, which provides the optimal signal integrity and jitter performance
Advanced Transmit (ATX) PLL	Low jitter ATX (LC tank based) PLLs with continuous tuning range to cover a wide range of standard and proprietary protocols
Fractional PLLs	On-chip fractional frequency synthesizers to replace on-board crystal oscillators and reduce system cost
Digitally Assisted Analog CDR	Superior jitter tolerance with fast lock time
Dynamic Partial Reconfiguration	Allows independent control of the Avalon memory-mapped interface of each transceiver channel for the highest transceiver flexibility
Multiple PCS-PMA and PCS- PLD interface widths	8-, 10-, 16-, 20-, 32-, 40-, or 64-bit interface widths for flexibility of deserialization width, encoding, and reduced latency

# **PCS Features**

This table summarizes the Intel Arria 10 transceiver PCS features. You can use the transceiver PCS to support a wide range of protocols ranging from 1 Gbps to 25.8 Gbps.



PCS	Description
Standard PCS	<ul> <li>Operates at a data rate up to 12 Gbps</li> <li>Supports protocols such as PCI-Express, CPRI 4.2+, GigE, IEEE 1588 in Hard PCS</li> <li>Implements other protocols using Basic/Custom (Standard PCS) transceiver configuration rules.</li> </ul>
Enhanced PCS	<ul> <li>Performs functions common to most serial data industry standards, such as word alignment, encoding/decoding, and framing, before data is sent or received off-chip through the PMA</li> <li>Handles data transfer to and from the FPGA fabric</li> <li>Handles data transfer internally to and from the PMA</li> <li>Provides frequency compensation</li> <li>Performs channel bonding for multi-channel low skew applications</li> </ul>
PCIe Gen3 PCS	<ul> <li>Supports the seamless switching of Data and Clock between the Gen1, Gen2, and Gen3 data rates</li> <li>Provides support for PIPE 3.0 features</li> <li>Supports the PIPE interface with the Hard IP enabled, as well as with the Hard IP bypassed</li> </ul>

#### **Related Information**

- PCIe Gen1, Gen2, and Gen3 Hard IP on page 26
- Interlaken Support on page 26
- 10 Gbps Ethernet Support on page 26

## **PCS Protocol Support**

This table lists some of the protocols supported by the Intel Arria 10 transceiver PCS. For more information about the blocks in the transmitter and receiver data paths, refer to the related information.

Protocol	Data Rate (Gbps)	Transceiver IP	PCS Support	
PCIe Gen3 x1, x2, x4, x8	8.0	Native PHY (PIPE)	Standard PCS and PCIe Gen3 PCS	
PCIe Gen2 x1, x2, x4, x8	5.0	Native PHY (PIPE)	Standard PCS	
PCIe Gen1 x1, x2, x4, x8	2.5	Native PHY (PIPE)	Standard PCS	
1000BASE-X Gigabit Ethernet	1.25	Native PHY	Standard PCS	
1000BASE-X Gigabit Ethernet with IEEE 1588v2	1.25	Native PHY	Standard PCS	
10GBASE-R	10.3125	Native PHY	Enhanced PCS	
10GBASE-R with IEEE 1588v2	10.3125	Native PHY	Enhanced PCS	
10GBASE-R with KR FEC	10.3125	Native PHY	Enhanced PCS	
10GBASE-KR and 1000BASE-X	10.3125	1G/10GbE and 10GBASE-KR PHY	Standard PCS and Enhanced PCS	
Interlaken (CEI-6G/11G)	3.125 to 17.4	Native PHY	Enhanced PCS	
SFI-S/SFI-5.2	11.2	Native PHY	Enhanced PCS	
10G SDI	10.692	Native PHY	Enhanced PCS	
			continued	



## Figure 9. HPS Block Diagram

This figure shows a block diagram of the HPS with the dual ARM Cortex-A9 MPCore processor.



# Key Advantages of 20-nm HPS

The 20-nm HPS strikes a balance between enabling maximum software compatibility with 28-nm SoCs while still improving upon the 28-nm HPS architecture. These improvements address the requirements of the next generation target markets such as wireless and wireline communications, compute and storage equipment, broadcast and military in terms of performance, memory bandwidth, connectivity via backplane and security.



# Table 24.Improvements in 20 nm HPS

This table lists the key improvements of the 20 nm HPS compared to the 28 nm HPS.

Advantages/ Improvements	Description
Increased performance and overdrive capability	While the nominal processor frequency is 1.2 GHz, the 20 nm HPS offers an "overdrive" feature which enables a higher processor operating frequency. This requires a higher supply voltage value that is unique to the HPS and may require a separate regulator.
Increased processor memory bandwidth and DDR4 support	Up to 64-bit DDR4 memory at 2,400 Mbps support is available for the processor. The hard memory controller for the HPS comprises a multi-port front end that manages connections to a single port memory controller. The multi-port front end allows logic core and the HPS to share ports and thereby the available bandwidth of the memory controller.
Flexible I/O sharing	<ul> <li>An advanced I/O pin muxing scheme allows improved sharing of I/O between the HPS and the core logic. The following types of I/O are available for SoC:</li> <li>17 dedicated I/Os—physically located inside the HPS block and are not accessible to logic within the core. The 17 dedicated I/Os are used for HPS clock, resets, and interfacing with boot devices, QSPI, and SD/MMC.</li> </ul>
	• 48 direct shared I/O—located closest to the HPS block and are ideal for high speed HPS peripherals such as EMAC, USB, and others. There is one bank of 48 I/Os that supports direct sharing where the 48 I/Os can be shared 12 I/Os at a time.
	• Standard (shared) I/O—all standard I/Os can be shared by the HPS peripherals and any logic within the core. For designs where more than 48 I/Os are required to fully use all the peripherals in the HPS, these I/Os can be connected through the core logic.
EMAC core	Three EMAC cores are available in the HPS. The EMAC cores enable an application to support two redundant Ethernet connections; for example, backplane, or two EMAC cores for managing IEEE 1588 time stamp information while allowing a third EMAC core for debug and configuration. All three EMACs can potentially share the same time stamps, simplifying the 1588 time stamping implementation. A new serial time stamp interface allows core logic to access and read the time stamp values. The integrated EMAC controllers can be connected to external Ethernet PHY through the provided MDIO or $I^2C$ interface.
On-chip memory	The on-chip memory is updated to 256 KB support and can support larger data sets and real time algorithms.
ECC enhancements	Improvements in L2 Cache ECC management allow identification of errors down to the address level. ECC enhancements also enable improved error injection and status reporting via the introduction of new memory mapped access to syndrome and data signals.
HPS to FPGA Interconnect Backbone	Although the HPS and the Logic Core can operate independently, they are tightly coupled via a high-bandwidth system interconnect built from high-performance ARM AMBA AXI bus bridges. IP bus masters in the FPGA fabric have access to HPS bus slaves via the FPGA-to-HPS interconnect. Similarly, HPS bus masters have access to bus slaves in the core fabric via the HPS-to-FPGA bridge. Both bridges are AMBA AXI-3 compliant and support simultaneous read and write transactions. Up to three masters within the core fabric can share the HPS SDRAM controller with the processor. Additionally, the processor can be used to configure the core fabric under program control via a dedicated 32-bit configuration port.
FPGA configuration and HPS booting	The FPGA fabric and HPS in the SoCs are powered independently. You can reduce the clock frequencies or gate the clocks to reduce dynamic power. You can configure the FPGA fabric and boot the HPS independently, in any order, providing you with more design flexibility.
Security	New security features have been introduced for anti-tamper management, secure boot, encryption (AES), and authentication (SHA).



# **Features of the HPS**

The HPS has the following features:

- 1.2-GHz, dual-core ARM Cortex-A9 MPCore processor with up to 1.5-GHz via overdrive
  - ARMv7-A architecture that runs 32-bit ARM instructions, 16-bit and 32-bit Thumb instructions, and 8-bit Java byte codes in Jazelle style
  - Superscalar, variable length, out-of-order pipeline with dynamic branch prediction
  - Instruction Efficiency 2.5 MIPS/MHz, which provides total performance of 7500 MIPS at 1.5 GHz
- Each processor core includes:
  - 32 KB of L1 instruction cache, 32 KB of L1 data cache
  - Single- and double-precision floating-point unit and NEON media engine
  - CoreSight debug and trace technology
  - Snoop Control Unit (SCU) and Acceleration Coherency Port (ACP)
- 512 KB of shared L2 cache
- 256 KB of scratch RAM
- Hard memory controller with support for DDR3, DDR4 and optional error correction code (ECC) support
- Multiport Front End (MPFE) Scheduler interface to the hard memory controller
- 8-channel direct memory access (DMA) controller
- QSPI flash controller with SIO, DIO, QIO SPI Flash support
- NAND flash controller (ONFI 1.0 or later) with DMA and ECC support, updated to support 8 and 16-bit Flash devices and new command DMA to offload CPU for fast power down recovery
- Updated SD/SDIO/MMC controller to eMMC 4.5 with DMA with CE-ATA digital command support
- 3 10/100/1000 Ethernet media access control (MAC) with DMA
- 2 USB On-the-Go (OTG) controllers with DMA
- 5 I<sup>2</sup>C controllers (3 can be used by EMAC for MIO to external PHY)
- 2 UART 16550 Compatible controllers
- 4 serial peripheral interfaces (SPI) (2 Master, 2 Slaves)
- 62 programmable general-purpose I/Os, which includes 48 direct share I/Os that allows the HPS peripherals to connect directly to the FPGA I/Os
- 7 general-purpose timers
- 4 watchdog timers
- Anti-tamper, Secure Boot, Encryption (AES) and Authentication (SHA)



Instead of placing all device functions in the FPGA fabric, you can store some functions that do not run simultaneously in external memory and load them only when required. This capability increases the effective logic density of the device, and lowers cost and power consumption.

In the Intel solution, you do not have to worry about intricate device architecture to perform a partial reconfiguration. The partial reconfiguration capability is built into the Intel Quartus Prime design software, making such time-intensive task simple.

Intel Arria 10 devices support partial reconfiguration in the following configuration options:

- Using an internal host:
  - All supported configuration modes where the FPGA has access to external memory devices such as serial and parallel flash memory.
  - Configuration via Protocol [CvP (PCIe)]
- Using an external host—passive serial (PS), fast passive parallel (FPP) x8, FPP x16, and FPP x32 I/O interface.

# **Enhanced Configuration and Configuration via Protocol**

## Table 25. Configuration Schemes and Features of Intel Arria 10 Devices

Intel Arria 10 devices support 1.8 V programming voltage and several configuration schemes.

Scheme	Data Width	Max Clock Rate (MHz)	Max Data Rate (Mbps) (13)	Decompression	Design Security <sup>(1</sup> 4)	Partial Reconfiguration (15)	Remote System Update
JTAG	1 bit	33	33	_	-	Yes <sup>(16)</sup>	-
Active Serial (AS) through the EPCQ-L configuration device	1 bit, 4 bits	100	400	Yes	Yes	Yes <sup>(16)</sup>	Yes
Passive serial (PS) through CPLD or external microcontroller	1 bit	100	100	Yes	Yes	Yes <sup>(16)</sup>	Parallel Flash Loader (PFL) IP core
	continued					ntinued	

<sup>&</sup>lt;sup>(13)</sup> Enabling either compression or design security features affects the maximum data rate. Refer to the Intel Arria 10 Device Datasheet for more information.

<sup>&</sup>lt;sup>(14)</sup> Encryption and compression cannot be used simultaneously.

<sup>&</sup>lt;sup>(15)</sup> Partial reconfiguration is an advanced feature of the device family. If you are interested in using partial reconfiguration, contact Intel for support.

<sup>&</sup>lt;sup>(16)</sup> Partial configuration can be performed only when it is configured as internal host.



Scheme	Data Width	Max Clock Rate (MHz)	Max Data Rate (Mbps) (13)	Decompression	Design Security <sup>(1</sup> 4)	Partial Reconfiguration (15)	Remote System Update
Fast passive	8 bits	100	3200	Yes	Yes	Yes <sup>(17)</sup>	PFL IP
parallel (FPP) through CPLD or	16 bits	]		Yes	Yes		core
external microcontroller	32 bits	]		Yes	Yes		
Configuration via	16 bits	100	3200	Yes	Yes	Yes <sup>(17)</sup>	_
HPS	32 bits			Yes	Yes		
Configuration via Protocol [CvP (PCIe*)]	x1, x2, x4, x8 lanes	-	8000	Yes	Yes	Yes <sup>(16)</sup>	_

You can configure Intel Arria 10 devices through PCIe using Configuration via Protocol (CvP). The Intel Arria 10 CvP implementation conforms to the PCIe 100 ms power-up-to-active time requirement.

# **SEU Error Detection and Correction**

Intel Arria 10 devices offer robust and easy-to-use single-event upset (SEU) error detection and correction circuitry.

The detection and correction circuitry includes protection for Configuration RAM (CRAM) programming bits and user memories. The CRAM is protected by a continuously running CRC error detection circuit with integrated ECC that automatically corrects one or two errors and detects higher order multi-bit errors. When more than two errors occur, correction is available through reloading of the core programming file, providing a complete design refresh while the FPGA continues to operate.

The physical layout of the Intel Arria 10 CRAM array is optimized to make the majority of multi-bit upsets appear as independent single-bit or double-bit errors which are automatically corrected by the integrated CRAM ECC circuitry. In addition to the CRAM protection, the M20K memory blocks also include integrated ECC circuitry and are layout-optimized for error detection and correction. The MLAB does not have ECC.

# **Power Management**

Intel Arria 10 devices leverage the advanced 20 nm process technology, a low 0.9 V core power supply, an enhanced core architecture, and several optional power reduction techniques to reduce total power consumption by as much as 40% compared to Arria V devices and as much as 60% compared to Stratix V devices.

<sup>&</sup>lt;sup>(13)</sup> Enabling either compression or design security features affects the maximum data rate. Refer to the Intel Arria 10 Device Datasheet for more information.

<sup>&</sup>lt;sup>(14)</sup> Encryption and compression cannot be used simultaneously.

<sup>&</sup>lt;sup>(15)</sup> Partial reconfiguration is an advanced feature of the device family. If you are interested in using partial reconfiguration, contact Intel for support.

<sup>&</sup>lt;sup>(17)</sup> Supported at a maximum clock rate of 100 MHz.



The optional power reduction techniques in Intel Arria 10 devices include:

- SmartVID—a code is programmed into each device during manufacturing that allows a smart regulator to operate the device at lower core V<sub>CC</sub> while maintaining performance
- **Programmable Power Technology**—non-critical timing paths are identified by the Intel Quartus Prime software and the logic in these paths is biased for low power instead of high performance
- Low Static Power Options—devices are available with either standard static power or low static power while maintaining performance

Furthermore, Intel Arria 10 devices feature Intel's industry-leading low power transceivers and include a number of hard IP blocks that not only reduce logic resources but also deliver substantial power savings compared to soft implementations. In general, hard IP blocks consume up to 90% less power than the equivalent soft logic implementations.

# **Incremental Compilation**

The Intel Quartus Prime software incremental compilation feature reduces compilation time and helps preserve performance to ease timing closure. The incremental compilation feature enables the partial reconfiguration flow for Intel Arria 10 devices.

Incremental compilation supports top-down, bottom-up, and team-based design flows. This feature facilitates modular, hierarchical, and team-based design flows where different designers compile their respective design sections in parallel. Furthermore, different designers or IP providers can develop and optimize different blocks of the design independently. These blocks can then be imported into the top level project.

# **Document Revision History for Intel Arria 10 Device Overview**

Document Version	Changes
2018.04.09	Updated the lowest $V_{CC}$ from 0.83 V to 0.82 V in the topic listing a summary of the device features.

Date	Version	Changes
January 2018	2018.01.17	• Updated the maximum data rate for HPS (Intel Arria 10 SX devices external memory interface DDR3 controller from 2,166 Mbps to 2,133 Mbps.
		<ul> <li>Updated maximum frequency supported for half rate QDRII and QDRII + SRAM to 633 MHz in <i>Memory Standards Supported by the Soft</i> <i>Memory Controller</i> table.</li> </ul>
		Updated transceiver backplane capability to 12.5 Gbps.
		• Removed transceiver speed grade 5 in <i>Sample Ordering Core and Available Options for Intel Arria 10 GX Devices</i> figure.
	1	continued